## Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

## **Listing of Claims**

(Currently Amended) A semiconductor device, comprising:
 a polysilicon gate electrode provided on a silicon substrate <u>not including SiGe</u>,
 wherein

said <u>polysilicon</u> gate electrode is subjected to compressive stress as internal stress therein, to apply tensile stress to said silicon substrate, and

ions having a mass number of 70 or more are implanted into said <u>polysilicon</u> gate electrode.

- 2. (Currently Amended) The semiconductor device according to claim 1, wherein said <u>polysilicon</u> gate electrode is a gate electrode of an n-channel MOS transistor.
- 3. (Original) The semiconductor device according to claim 2, wherein said ions having a mass number of 70 or more are operative to serve as those for forming a source and drain region of said n-channel MOS transistor.
  - 4. (Original) The semiconductor device according to claim 1, wherein said ions having a mass number of 70 or more are electrically inactive ions.
- 5. (Currently Amended) The semiconductor device according to claim 1, wherein said polysilicon gate electrode has a bird's beak at a lower edge portion thereof, said bird's beak being defined by a silicon oxide film.

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6. (Original) The semiconductor device according to claim 1, wherein said silicon substrate is a strained silicon substrate.

7-18 (Cancelled).